PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	IPG/15/9036
1.3 Title of PCN	Micro Leadframe Package conversion to High Density for E-Fuse product Family
1.4 Product Category	Linear Voltage Regulator
1.5 Issue date	2015-01-21

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Antonio RIVIERA
2.1.3 Quality Manager	Paolo MORETTI

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, ...)	CARSEM

4. Description of change

	Old	**New**
4.1 Description	STD FRAME, Au wire bonding, Molding compound G770HC, Glue for controller die 8006NS	Micro Lead-frame Package (MLP) built on standard Lead-frame will be converted to High Density Lead-frame (HDL) on E-Fuse product family assembled in FPN 3x3mm2 package in Carsem (Suzhou). We grabbed the opportunity to improve the bill of Material too by using a new Glue (HITACHI 4900GCN3) for the Controller Die, the Cu Wire Bonding and an upgraded dedicated molding compound (G770HCD) packaged in a MSL3. The combination of HDL and G770HCD has been already qualified and it is running in production on similar product/packages
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	The HDL implementation will bring to a higher production capability and to a better frame handling that it is translated in a better product quality. On the other hand these changes will harmonize the Bill of Material in CARSEM site.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	see traceability code

7. Timing / schedule

7.1 Date of qualification results	2014-12-18
7.2 Intended start of delivery	2015-03-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	250-W-14-UW70-STEF05WPUR in VDFPN 3x3-10L (New BOM)-PCN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2015-01-21

9. Attachments (additional documentations)

9036PpPrdtLst.pdf
250-W-14-UW70-STEF05WPUR in VDFPN 3x3-10L (New BOM)-PCN.pdf

10. Affected parts

10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STEF05DPUR	
	STEF05PUR	
	STEF12PUR	

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